

AMENDMENTS TO THE CLAIMS

Please amend the claims as indicated below:

1 1. (Currently amended) An electronic circuit
2 equipment using a multilayer circuit board on which a
3 semiconductor chip is mounted, comprising:
4 a thin film capacitor provided on said multilayer
5 circuit board, wherein a first electrode of said thin film
6 capacitor and a first wiring of said multilayer circuit
7 board, which wiring is formed of a metal different from a
8 metal of said first electrode, are electrically connected
9 to each other, a second electrode of said thin film
10 capacitor and a second wiring of said multilayer circuit
11 board being electrically connected to each other, and a
12 thin film dielectric of said thin film capacitor is formed
13 by being grown epitaxially with said first electrode as its
14 base.

1 2. (Original) The electronic circuit equipment using
2 said multilayer circuit board as claimed in Claim 1,
3 wherein said multilayer circuit board includes a resin and
4 a conductor, said thin film capacitor is buried in said
5 resin, and at least one of electrical connections between

6 said wirings and said electrodes is established via a hole
7 bored in said resin.

1 3. (Currently amended) The electronic circuit
2 equipment using said multilayer circuit board as claimed in
3 Claim 1, wherein said first electrode and said first wiring
4 ~~are formed of materials different from each other, and have~~
5 the same pattern, and are laminated.

1 4. (Currently amended) An electronic circuit
2 equipment using a multilayer circuit board on which a
3 semiconductor chip is mounted, comprising:
4 a thin film capacitor provided on said multilayer
5 circuit board, wherein a first electrode of said thin film
6 capacitor and a first wiring of said multilayer circuit
7 board, which wiring is formed of a metal different from a
8 metal of said first electrode, are electrically connected
9 to each other, a second electrode of said thin film
10 capacitor and a second wiring of said multilayer circuit
11 board being electrically connected to each other, and a
12 thin film dielectric of said thin film capacitor is formed
13 by being grown epitaxially with said first electrode as its
14 base ~~The electronic circuit equipment using said multilayer~~

15 ~~circuit board as claimed in Claim 1~~, wherein an area of
16 said second electrode is narrower than an area of said thin
17 film dielectric, and said second electrode is located on an
18 inner side of said thin film dielectric.

1 5. (Original) The electronic circuit equipment using
2 said multilayer circuit board as claimed in Claim 1,
3 wherein, in order to prevent an electrical short-circuit
4 between said first electrode and said second electrode,
5 said electrodes are insulated from each other with a
6 material that is the same as a material of said thin film
7 dielectric.

1 6. (Original) The electronic circuit equipment using
2 said multilayer circuit board as claimed in Claim 1,
3 wherein said first electrode is a metal selected from a
4 group including Ru, Pt, and Pd.

1 7. (Original) The electronic circuit equipment using
2 said multilayer circuit board as claimed in Claim 6,
3 wherein said thin film dielectric is formed of strontium
4 titanate.

1 8. (Original) The electronic circuit equipment using
2 said multilayer circuit board as claimed in Claim 1,
3 wherein said first electrode has a first connection layer
4 positioned on a plane of said first electrode opposite to
5 said thin film dielectric and formed of a metal different
6 from a conductor of said first electrode, said first
7 connection layer being a metal selected from a group
8 including Cr, Mo, and Ti.

1 9. (Original) The electronic circuit equipment using
2 said multilayer circuit board as claimed in Claim 1,
3 wherein said second electrode has a second connection layer
4 positioned on a plane facing said thin film dielectric and
5 formed of a metal different from a conductor of said second
6 electrode, said second connection layer being a metal
7 selected from a group including Cr, Mo, and Ti.

1 10. (Currently amended) The electronic circuit
2 equipment using said multilayer circuit board as claimed in
3 Claim 1, wherein, one of said first electrode and said
4 second electrode, which faces ~~an electrode that is~~
5 ~~positioned nearer to~~ a conductor of a transmission line

6 formed on said multilayer circuit board is set at a
7 grounding potential.

1 11. (New) A multi-layer electronic circuit board
2 having an embedded thin film capacitor comprising:
3 a first dielectric circuit board layer;
4 a first electrically conductive layer supported on
5 said first dielectric layer;
6 an electrode layer supported on said first
7 electrically conductive layer, said electrode layer being a
8 metal and having a composition different from that of said
9 first electrically conductive layer;
10 an epitaxial dielectric layer supported on said
11 electrode layer;
12 a metallic connection layer overlying said epitaxial
13 dielectric layer and in contact therewith;
14 a second electrically conductive layer overlying and
15 in contact with said metallic connection layer; and
16 a second circuit board dielectric layer covering said
17 second electrically conductive layer.

1 12. (New) The multi-layer electronic circuit board of
2 claim 11, wherein said metal of said electrode layer is
3 selected from the group consisting of Ru, Pt, and Pd.

1 13. (New) The multi-layer electronic circuit board of
2 claim 11, wherein said epitaxial dielectric layer is
3 strontium titanate..

1 14. (New) The multi-layer electronic circuit board of
2 claim 11, wherein said metallic connection layer is
3 selected formed from a metal selected from the group
4 consisting of Cr, Mo, and Ti.